

Adjustable Majority Voting Algorithm for Stability Improvement in SRAM-based CMOS PUFs

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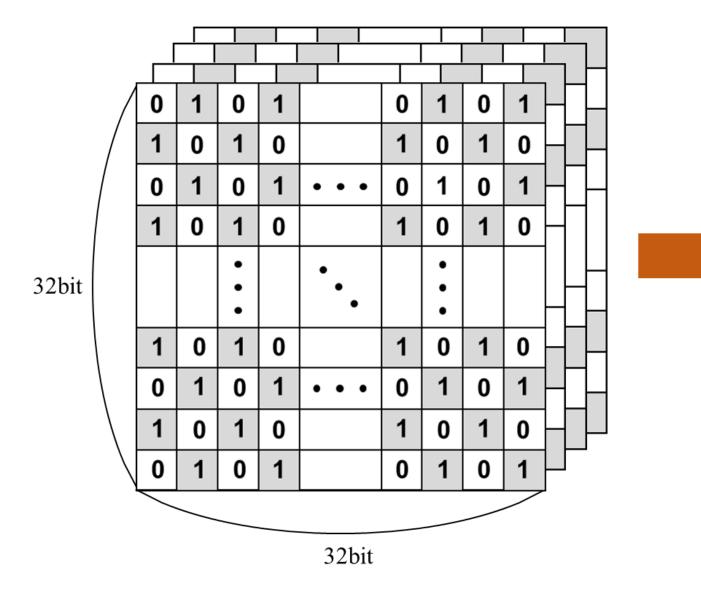
Abstract

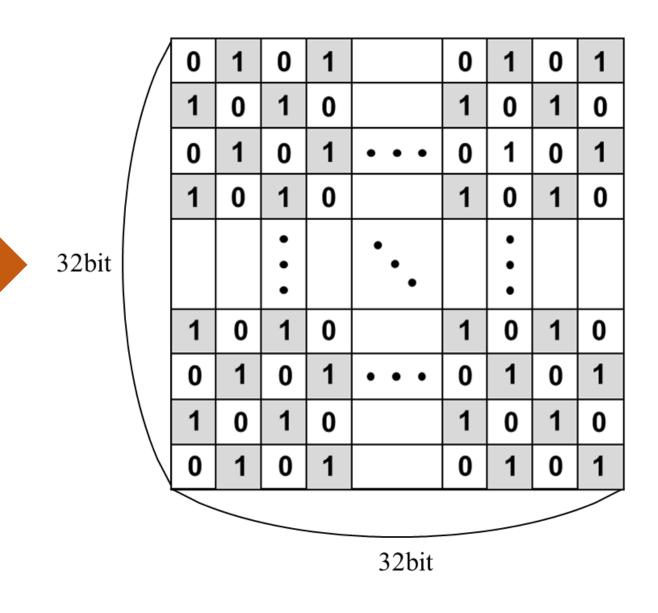
The SRAM-based CMOS physically unclonable function (PUF) employing the adjustable majority voting algorithm is presented. In memory-based PUFs with limited challenge-response pairs (CRPs), output stability is critical. To achieve a target bit error rate (BER), an error-correction algorithm using a user-configurable majority voting scheme is implemented using a data accumulator and majority selector. Fabricated in 28nm CMOS, the 1024-bit SRAM PUF core achieves 24.12 µm²/bit area and 0.09 pJ/bit energy efficiency. With 2¹⁰+1 repetitions, unstable bits reduce from 31.54% to 8.40%, and BER improves from 6.28% to 0.93%. Utilizing all SRAM bitcells, unstable bits and BER improve by 73.37% and 85.19%, respectively, at 1.0 V and 25°C. Consequently, masking only about 1% of the error cells leads to a zero BER. Furthermore, the inter-die and intra-die Hamming distances are 49.84% and 1.37% (1,000 evaluations), respectively.

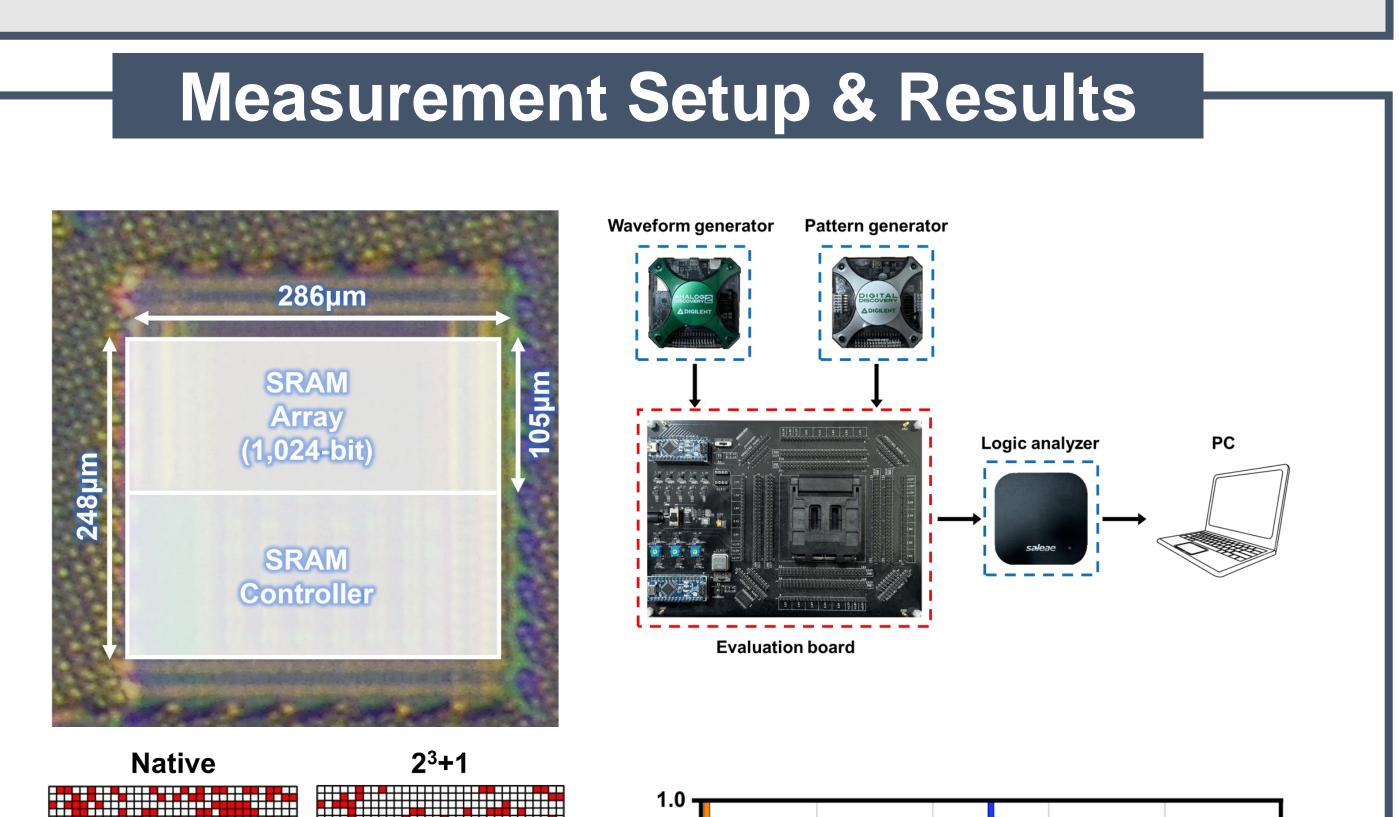
Concept of technique

- Conventional error-correction algorithm
- Discard unstable SRAM bit-stream "Reduction of active bits"
- Majority Voting algorithm

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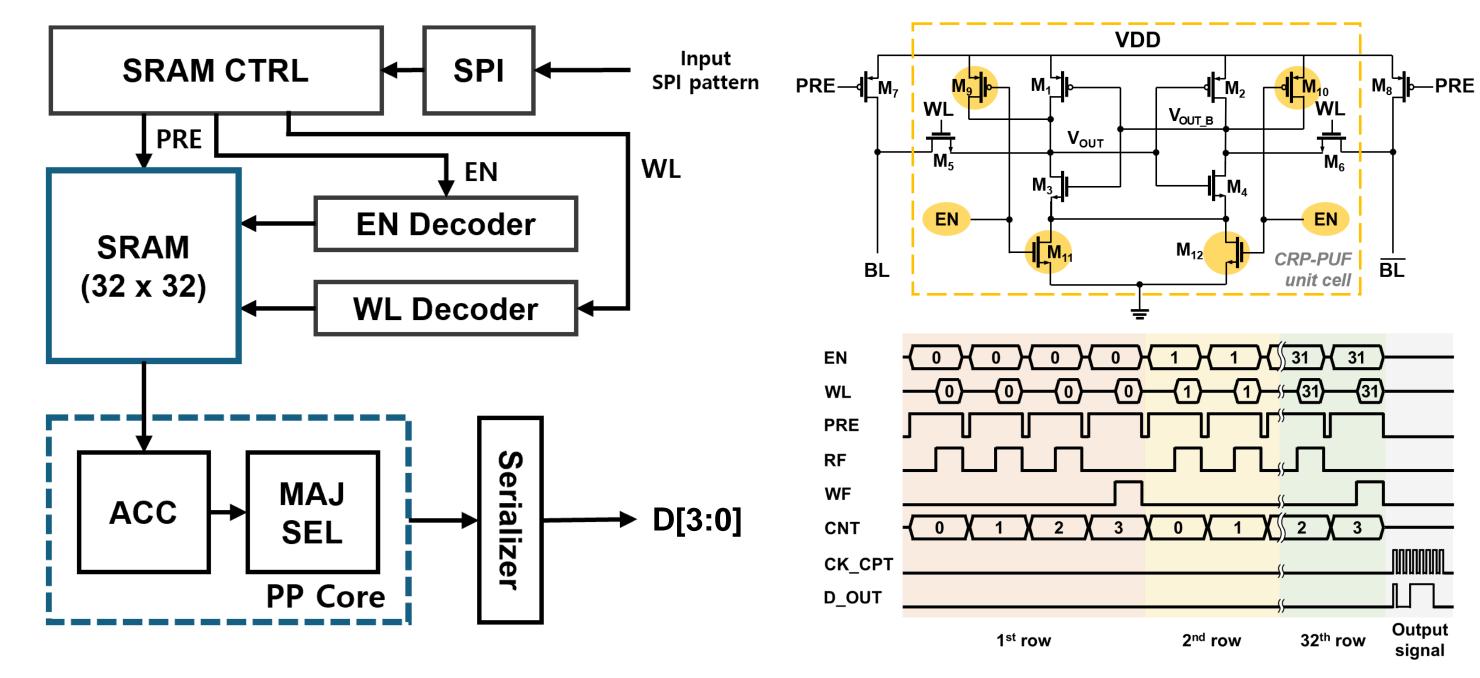


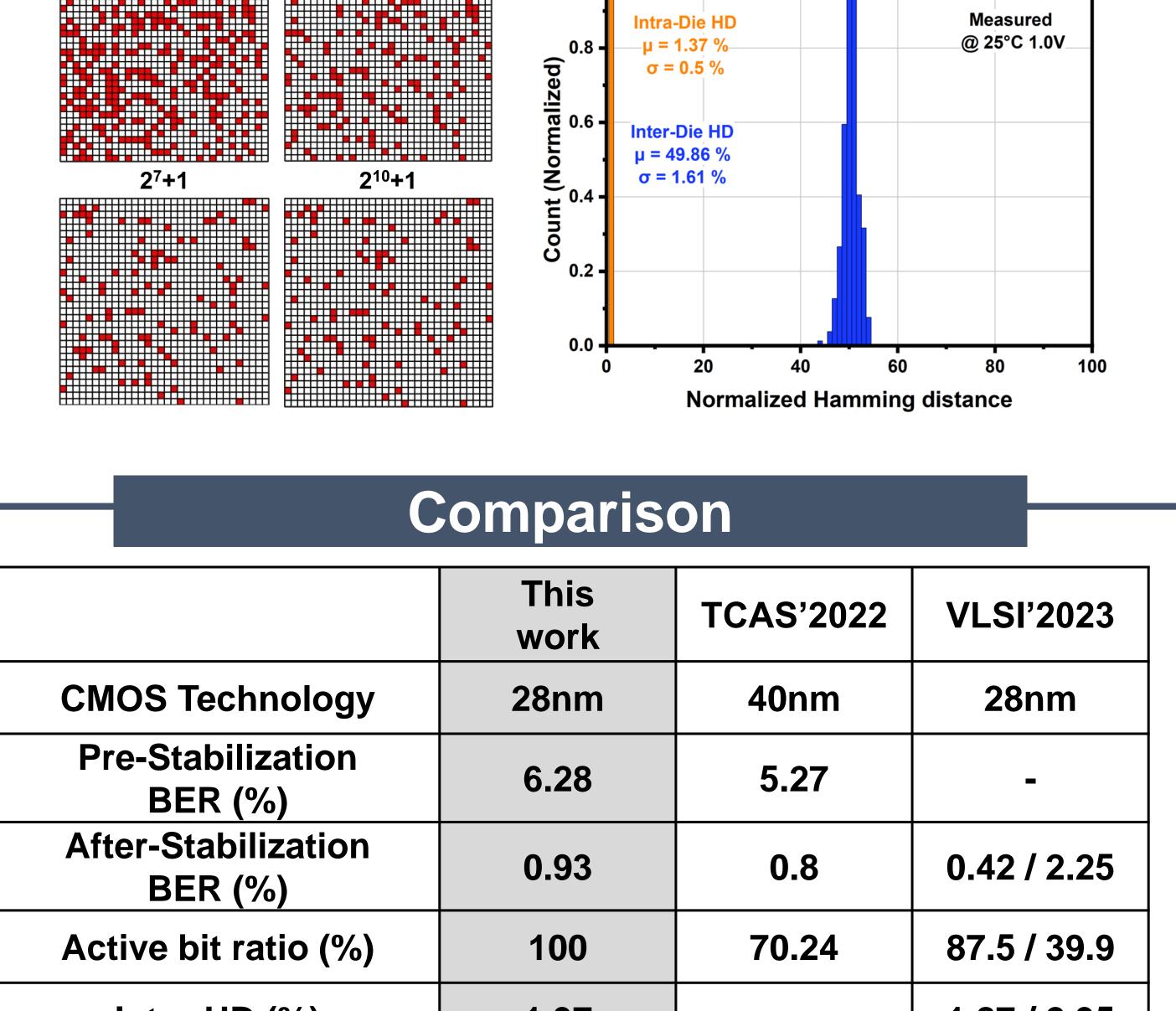




- Set the number of iteration cycles using the 'user-configurable option'.
- The chip internally averages multiple SRAM cell trials and outputs a single 32x32 bit array.
- Increasing the number of trials mitigates noise, yielding a more stable SRAM cell output and utilizing a more active bits.

Overall Architecture





- ♦ 32 x 32 SRAM PUF with multiple CRPs (1.6E+8).
- An adjustable majority voting scheme is implemented using an accumulator and majority selector.
- ◆ The prototype is fabricated in 28nm technology.

Intra-HD (%)	1.37	-	1.87 / 2.95
Inter-HD (%)	49.84	49.84	50.11 / 50.09
Acknowledgement			
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